



Specifications

This specifications is for wire per UL style 1423, solid silver-plated oxygen free copper
No voltage ratings for any size

Wire Gauge	30AWG
Conductor Material	Silver plated oxygen free, high conductivity copper per ASTM-B 170 grade
Plating Material	Minimum 40 microns per ASTM-B-298
Conductor Diameter	0.25mm
Conductor Elongation	20% before insulation
Insulation Material	Kynar 460
Insulation Average Wall Thickness	0.15mm
Total Diameter	0.5mm
Conductor Resistance ohms / 1,000 feet at 20°C	106
Spark Test	2,000V ACrms
Maximum Service Temperature	105°C

Test Requirements

100% per UL style 1,423 and subject 758

Dielectric : 2,000 V ac rms spark test

DCR : 106Ω / 100 feet maximum at 20°C

Part Number Table

Description	Part Number
Wire, Kynar, 30AWG, Black, 100m	100-30BK

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